Silicon N-Channel Power MOS FET Module

HITACHI

Application

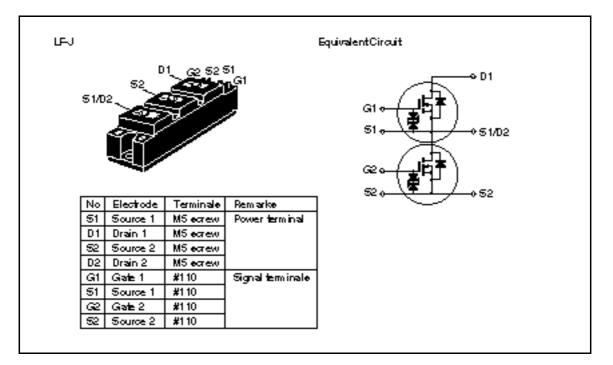
High Speed Power Switching

Features

- Equipped with Power MOS FET
- Low on-resistance
- High speed switching
- Low drive current
- Wide area of safe operation
- Inherent parallel diode between source and drain
- Isolated base from Terminal
- Suitable for motor driver, switching regulator and etc.



Outline



Absolute Maximum Ratings (Ta = 25°C) (Per FET chip)

Symbol	Rating	Unit V	
V _{(BR)DSS}	500		
V _{(BR)GSS}	±30	V	
I _D	75	А	
l _{D(peak)}	180	А	
I _{DR}	75	А	
I DR(peak)	180	А	
Pch*1	300	W	
Tch	150	°C	
Tstg	-45 to +125	°C	
Viso*2	2000	Vrms	
	V(BR)DSS V(BR)GSS ID ID(peak) IDR IDR(peak) Pch*1 Tch Tstg	V 500 V 500 ID 500 ID 75 ID 75 IDD 75 IDD 75 IDD 75 IDDR 75 IDDR 75 IDDR 75 IDDR 75 IDDR 180 Pch*1 300 Tch 150 Tstg -45 to +125	

Notes: 1. Value at Ta = 25°C

2. Base to terminals AC minute

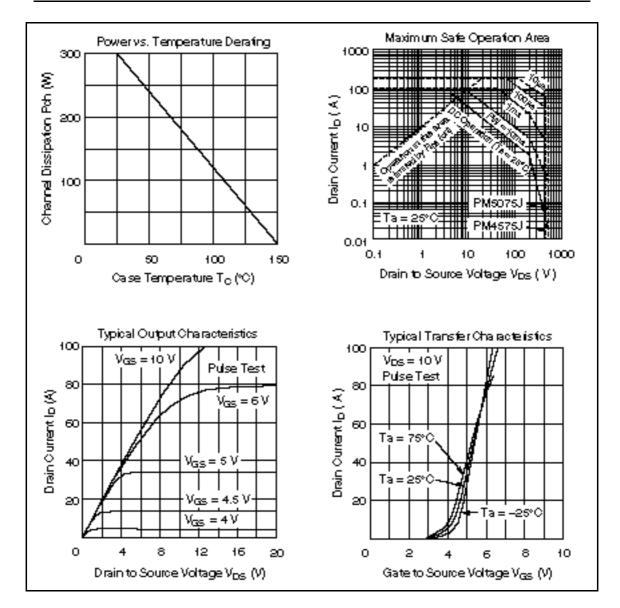
Item	Symbol	Min	Тур	Max	Unit	Test Condition
Drain to source breakdown voltage	$V_{(\text{BR})\text{DSS}}$	500	_	_	V	$I_{D} = 10 \text{ mA}, V_{GS} = 0 \text{ V}$
Gate to source leak current	I _{GSS}		_	±10	μA	$V_{\text{GS}} = \pm 25 \text{ V}, V_{\text{DS}} = 0 \text{ V}$
Gate to source breakdown voltage	$V_{(\text{BR})\text{GSS}}$	±30	_	_	V	$I_{g} = \pm 100 \ \mu A, \ V_{DS} = 0 \ V$
Drain leak current	I _{DSS}		_	500	μA	$V_{\rm DS} = 400 \ V, \ V_{\rm GS} = 0 \ V$
Gate to source threshold voltage	$V_{\text{GS(th)}}$	2.0	_	3.0	V	$I_{\rm D} = 1 \text{ mA}, V_{\rm DS} = 10 \text{ V}$
Drain to source saturation voltage	$V_{\text{DS(on)}}$		3.7	4.44	V	$I_{\rm D} = 37$ A, $V_{\rm GS} = 10$ V* ¹
Static drain-source on state resistance	$R_{\text{DS(on)}}$		0.10	0.12		$I_{\rm D} = 37$ A, $V_{\rm GS} = 10$ V*1
Forward transfer admittance	y _{fs}	_	45	_	S	$I_{\rm D} = 37$ A, $V_{\rm DS} = 10$ V ^{*1}
Input capacitance	Ciss		9600		pF	$V_{\rm DS} = 10 \ V, \ V_{\rm GS} = 0 \ V$
Output capacitance	Coss		2300			f = 1 MHz
Reverse transfer capacitance	Crss		330		_	
Turn-on delay time	t _{d(on)}		100		ns	$I_{\rm D} = 37$ A, $V_{\rm GS} = 10$ V
Rise time	t _r		310	_	_	Rg = 50
Turn-off delay time	t _{d(off)}	_	550	_	-	R _L = 1
Fall time	t _f	_	135	_	_	
Body to drain diode forward voltage	V_{DF}		1.8	—	V	$I_F = 75 \text{ A}, V_{GS} = 0 \text{ V}$
Body to drain diode reverse recovery time	t _{rr}	_	130	_	ns	$I_F = 75 \text{ A}, V_{GS} = 0 \text{ V}$ di/dt = 100 A/ μ s

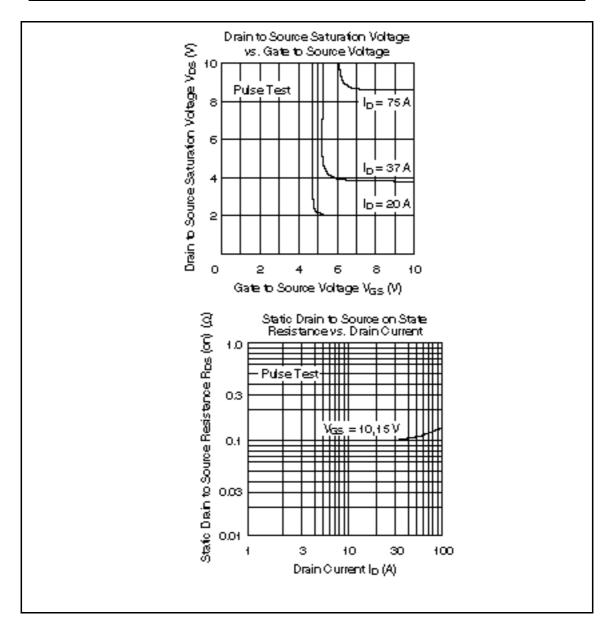
Electrical Characteristics (Ta = 25°C) (Per FET chip)

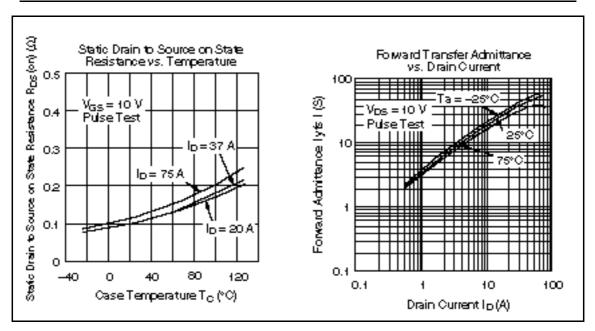
Note: 1. Pulse Test

Mechanical Characteristics

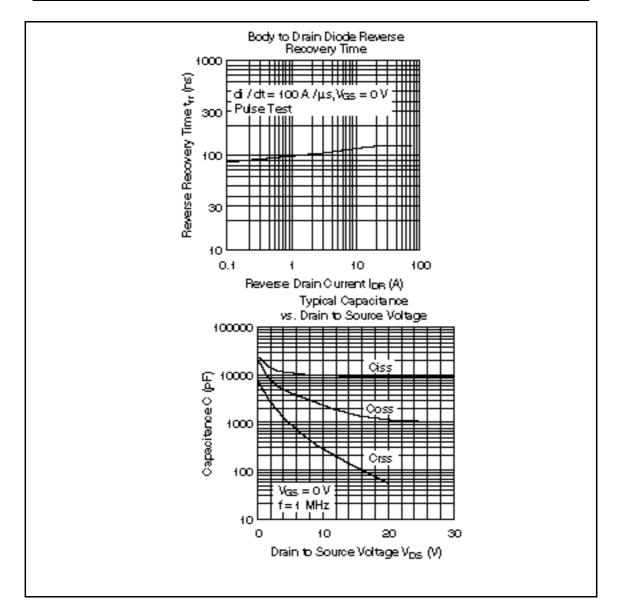
Symbol	Condition	Rating	Unit
_	Mounting into main-terminal with M4 screw	1.45 to 1.95	N-m
—	Mounting into heat sink with M5 screw	1.95 to 2.9	N-m
_	Typical value	200	g
	Symbol 	 Mounting into main-terminal with M4 screw Mounting into heat sink with M5 screw 	- Mounting into main-terminal with M4 screw 1.45 to 1.95 - Mounting into heat sink with M5 screw 1.95 to 2.9

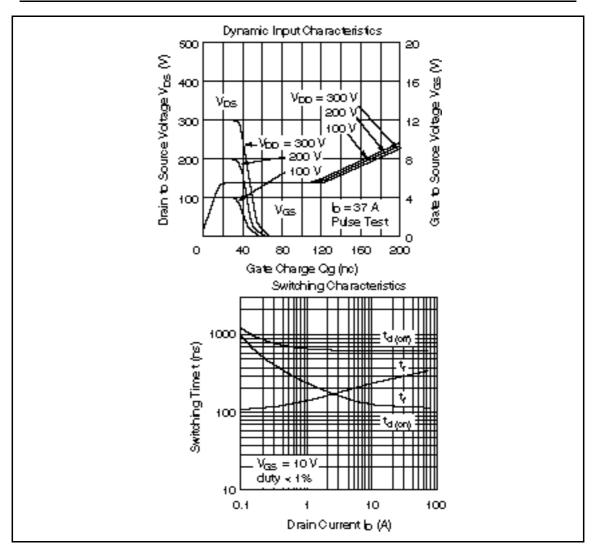


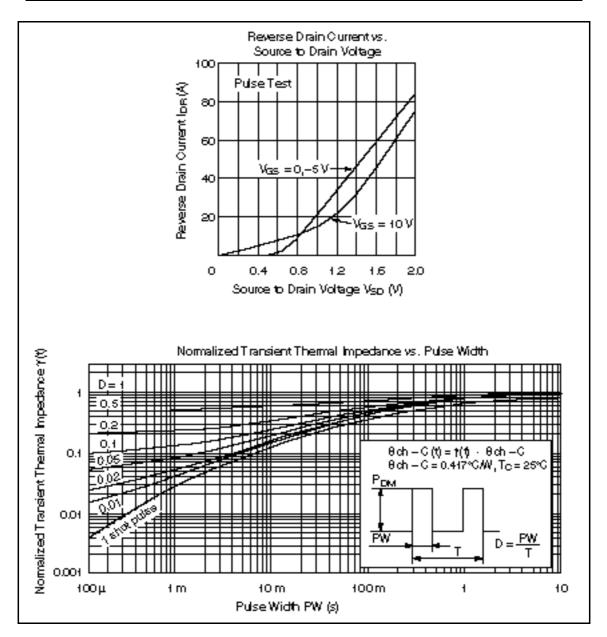


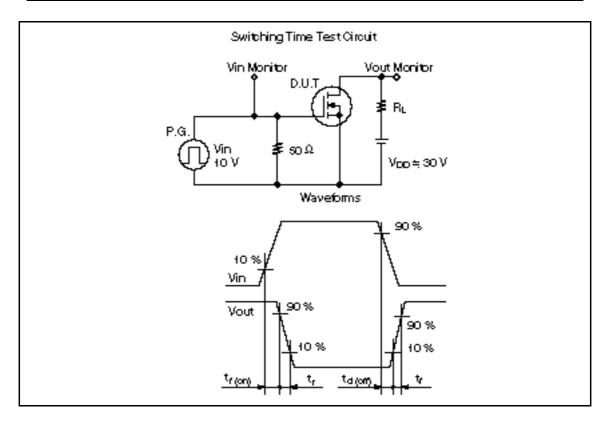


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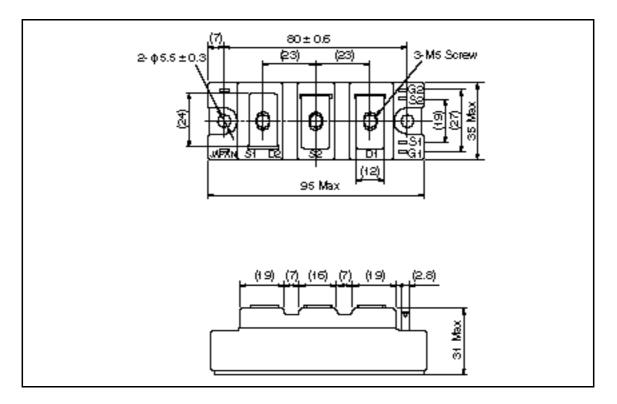






Package Dimensions

Unit: mm



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